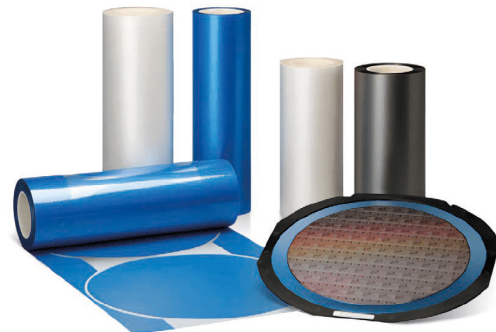


D series

UV Curable Dicing Tape

Adwill D-Series is an epoch-making line of UV curable dicing tapes whose features can be changed in accordance with operational processes. The tape's strong adhesion secures wafers during dicing and is then reduced by UV irradiation to facilitate pick-up. D-Series tape is essential for high quality full-cut wafer dicing and is fully applicable to dies of multiple sizes.

- Secures wafers with strong initial adhesion to ensure dicing without any slipping or peeling – even for small dies
- Supports instant control of adhesion by UV irradiation, allowing even large dies to be picked up easily
- Causes no contamination by metal ions or adhesive residues on the wafer backside surface, as well as no adverse UV irradiation effects on IC chips



Application	Feature	Base Material	Tape Name
Si Wafer	Standard	PVC	D-175D* / D-176D / D-171WD
Compound Semiconductor (SiC, GaN, etc.)		PO	D-489H / D-675C / D-686H / D-670C
	Heat Resistant	PO	D-435T
	Antistatic	PVC	D-820
		PO	D-888H / D-850T(S) / D-830J
	High Adhesion	PVC	D-171D
		PO	D-611 / D-611H
Glass / Ceramics		PVC	D-171D / D-175D* / D-176D
	Standard	PET	D-210NC / D-241 / D-218 / D-203(S)
		PO	D-841
Package Substrate	Standard	PO	D-510TC
	Antistatic	PO	D-825W / D-841 / D-847W / D-896W
Stealth Dicing	Singulation by Expansion	PVC	D-176D
		PO	D-678
	Singulation by Expansion / Through Tape Laser	PVC	D-821HSD
		PO	D-455H / D-458J
Laser Dicing	Full-Cut Laser	Special Elastomer	D-765
Wafer with LC Tape	Standard	PO	D-676C / D-676HC / D-686H
TAIKO® Wafer	Standard	PVC	D-176D / D-171D
		PO	D-485H / D-485W
Plasma Dicing	Standard	PO	D-485H / D-611 / D-611H / D-686H